

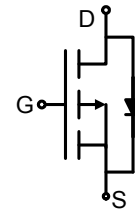
P-Channel Power MOSFET

General Features

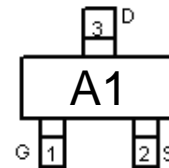
- $V_{DS} = -20V, I_D = -2.8A$
 $R_{DS(ON)} < 142m\Omega @ V_{GS} = -2.5V$
 $R_{DS(ON)} < 112m\Omega @ V_{GS} = -4.5V$
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- DC/DC Converter
- Load switch



Schematic diagram



Marking and pin assignment



SOT-23 top view

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	-2.8	A
Drain Current -Pulsed ^(Note 1)	I_{DM}	-10	A
Maximum Power Dissipation	P_D	0.4	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	312.5	$^\circ C/W$
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Electrical Characteristics ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-20		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$	-	-	-1	μA

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 8V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4		-1	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-2.8A$	-	90	112	m Ω
		$V_{GS}=-2.5V, I_D=-2.0A$	-	110	142	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-2.8A$	-	6.5	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{ISS}	$V_{DS}=-10V, V_{GS}=0V,$ $F=1.0MHz$	-	405	-	PF
Output Capacitance	C_{OSS}		-	75	-	PF
Reverse Transfer Capacitance	C_{RSS}		-	55	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V,$ $R_L=10\Omega, I_D=-1A,$ $V_{GEN}=-4.5V, R_g=1\Omega$	-	11	20	nS
Turn-on Rise Time	t_r		-	35	60	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	50	nS
Turn-Off Fall Time	t_f		-	10	20	nS
Total Gate Charge	Q_g	$V_{DS}=-10V, I_D=-3A,$ $V_{GS}=-4.5V$	-	5.5	10	nC
Gate-Source Charge	Q_{gs}		-	3.3	6	nC
Gate-Drain Charge	Q_{gd}		-	1.3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=-0.7A$	-	-0.8	-1.2	V
Diode Forward Current (Note 2)	I_S		-	-	-1.3	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

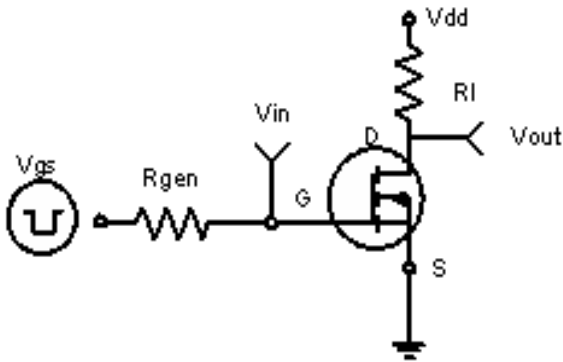


Figure 1: Switching Test Circuit

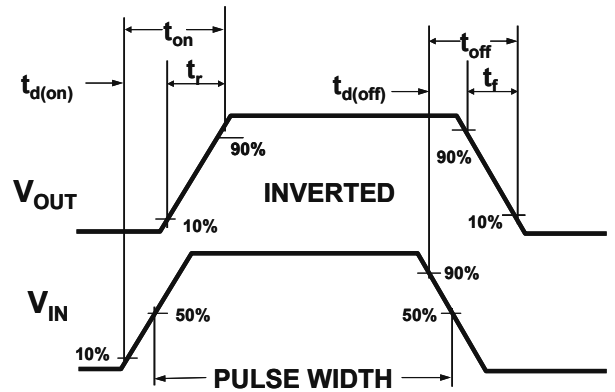


Figure 2: Switching Waveforms

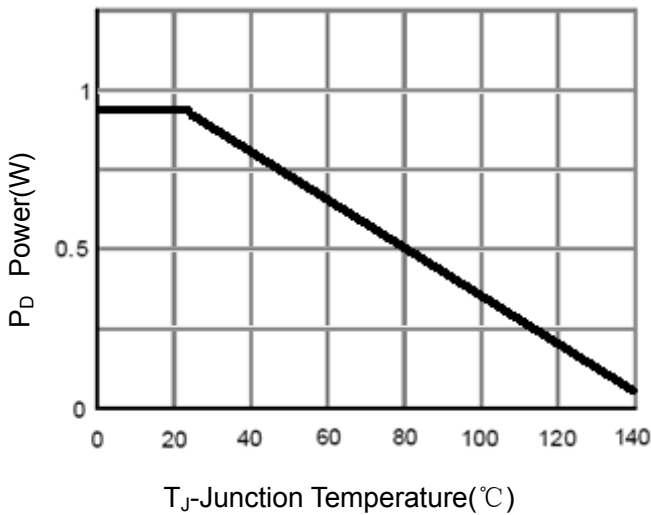


Figure 3 Power Dissipation

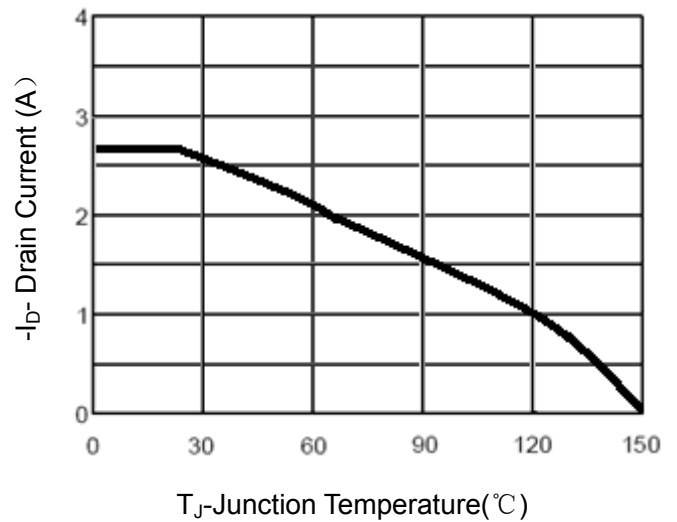


Figure 4 Drain Current

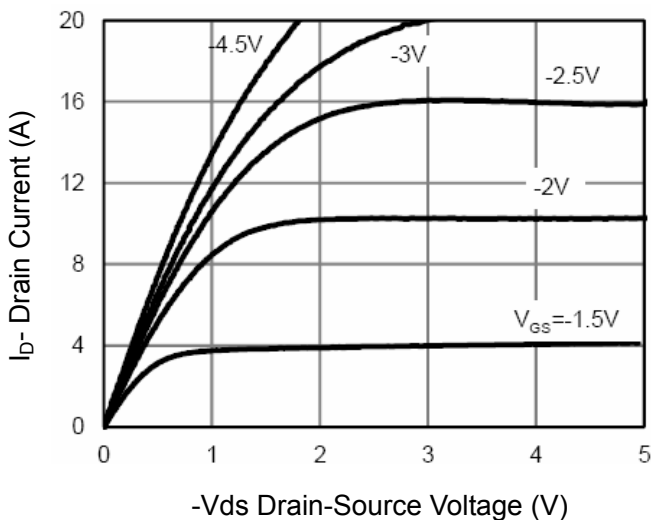


Figure 5 Output Characteristics

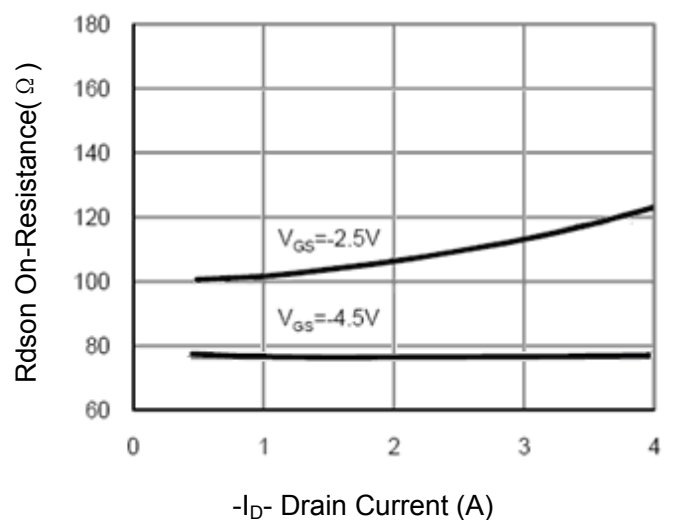


Figure 6 Drain-Source On-Resistance

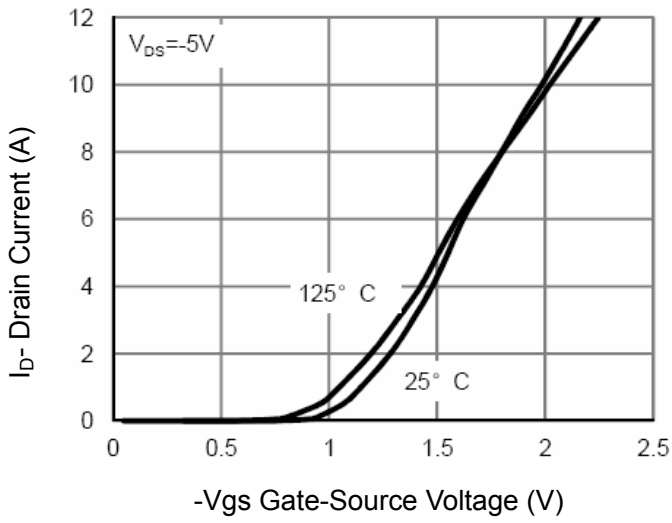


Figure 7 Transfer Characteristics

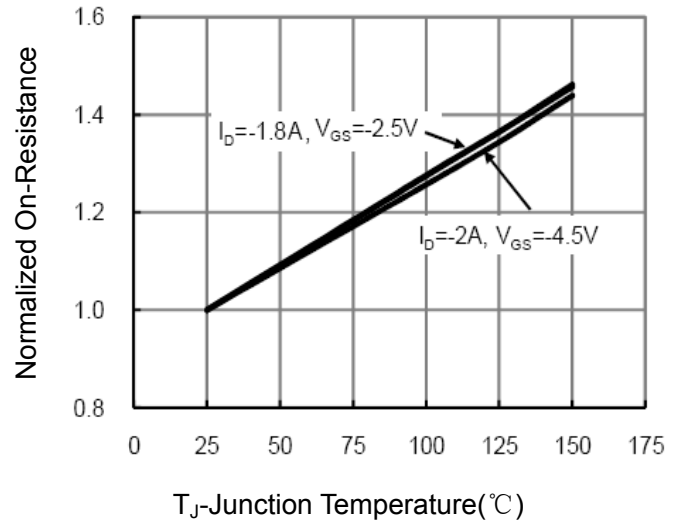


Figure 8 Drain-Source On-Resistance

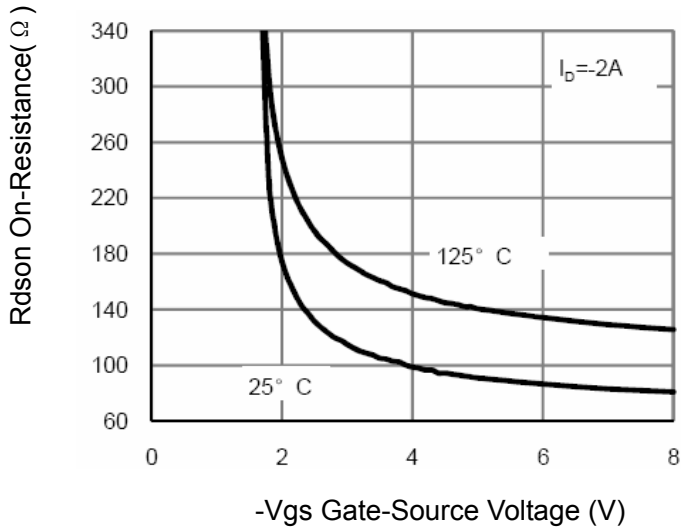


Figure 9 Rdson vs Vgs

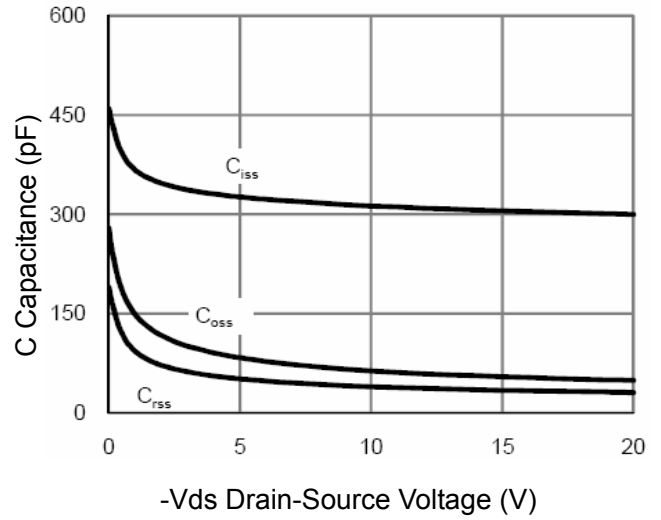


Figure 10 Capacitance vs Vds

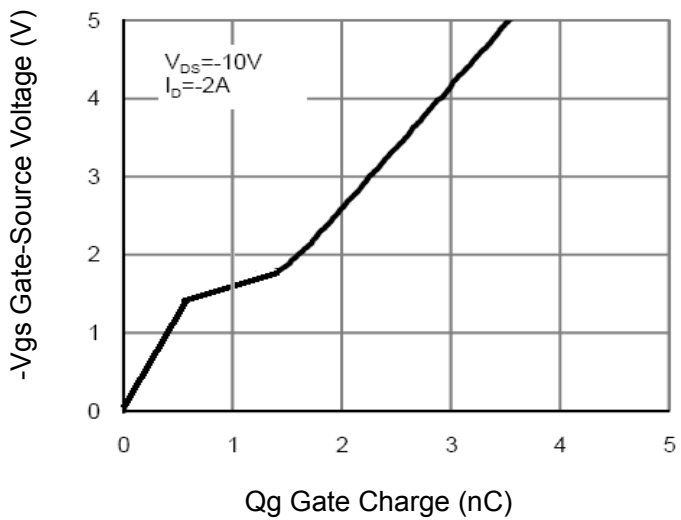


Figure 11 Gate Charge

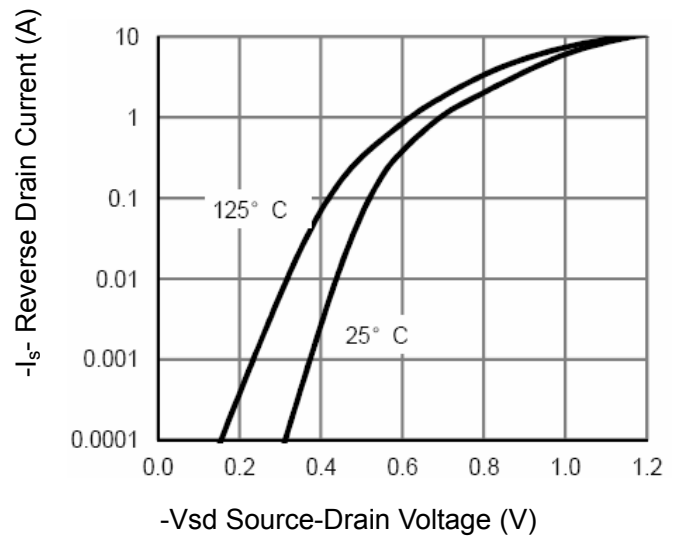


Figure 12 Source- Drain Diode Forward

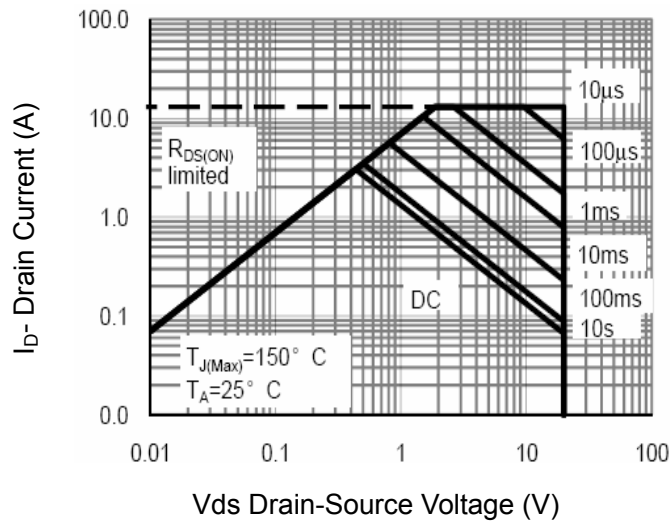


Figure 13 Safe Operation Area

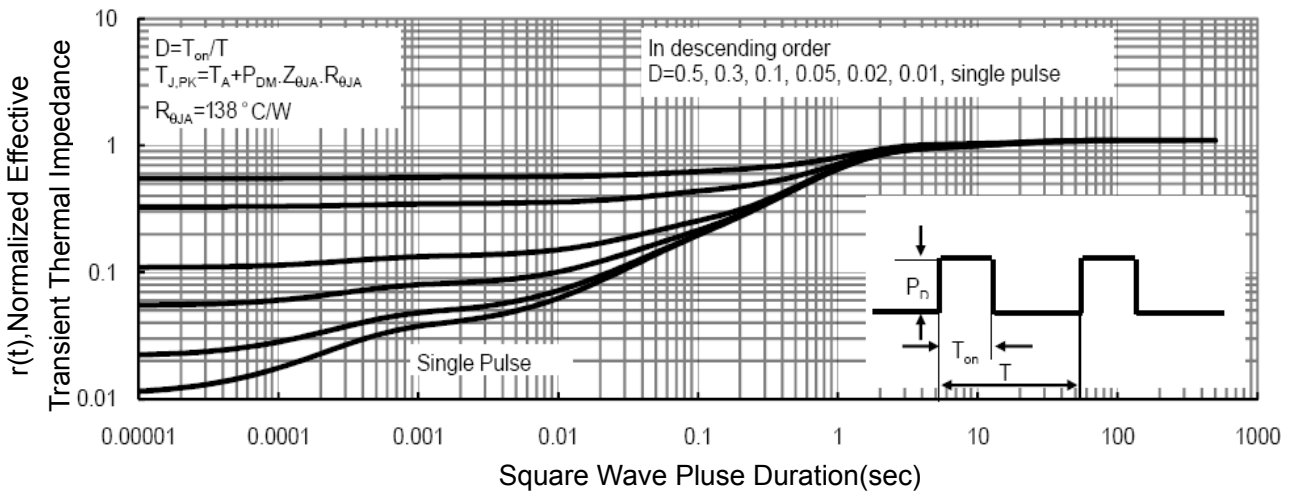
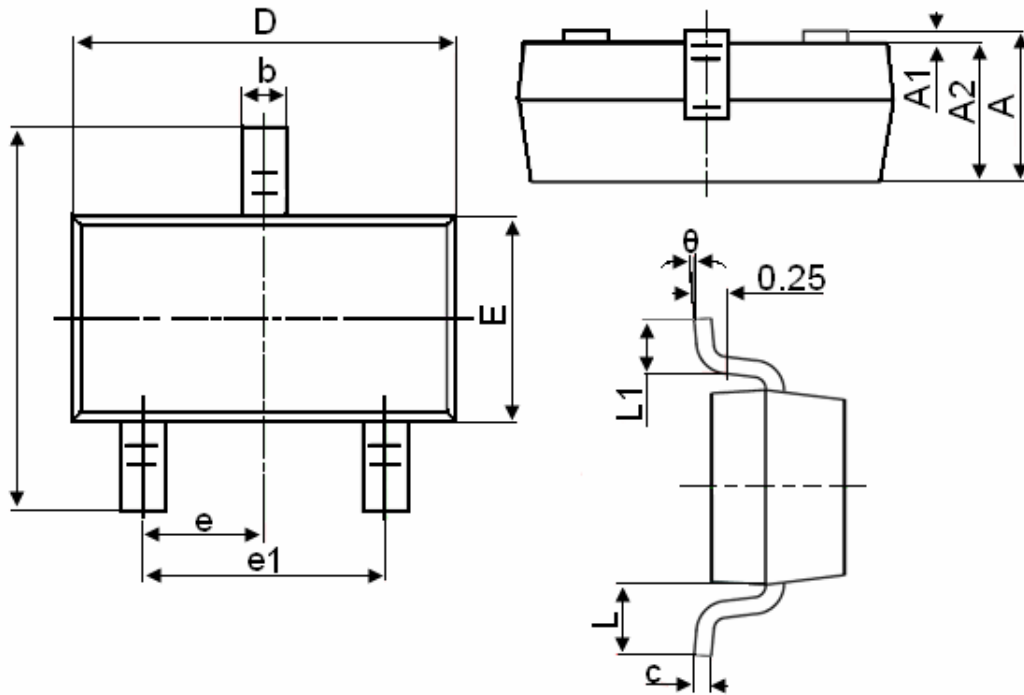


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT-23 Package Information


Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°